WHAT IS CLAIMED IS:

1. An IC chip for providing an exciting current to an MI element of an MI sensor, which MI element detects an external magnetic field, the MI chip comprising:

an MI element electrode to which the MI element is connected;

a switch unit that, in response to a pulse signal, provides the MI element with the exciting current via said MI element electrode; and

a first power supply electrode through which said switch unit is provided with electric power;

the IC chip having a first side face and a second side face opposite the first side face;

wherein

said MI element electrode is disposed in a neighborhood of the first side face; and

said first power supply electrode is disposed in a neighborhood of the second side face.

2. The IC chip as claimed in claim 1, wherein said MI element electrode, said switch unit, and said first power supply electrode are disposed substantially linearly.

3. The IC chip as claimed in claim 1, further comprising:

a detected signal electrode to which a detected signal is provided from the MI element;

a signal processing unit that receives the detected signal via said detected signal electrode and processes the received detected signal; and

a second power supply electrode through which said signal processing unit is provided with electric power;

wherein

said detected signal electrode is disposed in a neighborhood of the first side face; and

said second power supply electrode is

disposed in a neighborhood of the second side face.

4. The IC chip as claimed in claim 3, wherein the electric power is provided to said switch unit and said signal processing unit through different power supply wirings.

5. The IC chip as claimed in claim 3, wherein said switch unit and said signal processing unit are connected to different ground lines.

6. An IC chip for providing via an MI element electrode an exciting current to an MI element of an MI sensor, the IC chip comprising:

a switch unit that, in response to a pulse signal, provides the MI element with the exciting

current via the MI element electrode; and

a signal processing unit that receives a detected signal from the MI element and processes the received detected signal;

wherein

electric power is provided to said switch unit and said signal processing unit through different power supply wirings.

7. The IC chip as claimed in claim 6, wherein said switch unit and said signal processing unit are connected to different ground lines.

8. An MI sensor, comprising:

an MI element for detecting an external magnetic field; and

an IC chip for providing an exciting current to the MI element;

wherein

said IC chip comprises:

an MI element electrode to which the MI element is connected;

a switch unit that, in response to a pulse signal, provides said MI element with the exciting current via said MI element electrode; and

a first power supply electrode through which said switch unit is provided with electric power;

wherein said IC chip has a first side face and a second side face opposite the first side face; and

wherein

said MI element electrode is disposed in a neighborhood of the first side face; and

said first power supply electrode is disposed in a neighborhood of the second side face.

9. The MI sensor as claimed in claim 8, wherein said MI element electrode, said switch unit, and said first power supply electrode are disposed substantially linearly.

10. The MI sensor as claimed in claim 8, wherein

said IC chip further comprises:

a detected signal electrode to which a detected signal is provided from said MI element;

a signal processing unit that receives the detected signal via said detected signal electrode and processes the received detected signal; and

a second power supply electrode through which said signal processing unit is provided with the electric power;

wherein

said detected signal electrode is disposed in a neighborhood of the first side face; and

said second power supply electrode is disposed in a neighborhood of the second side face.

11. The MI sensor as claimed in claim 10,

wherein the electric power is provided to said switch unit and said signal processing unit through different power supply wirings.

12. The MI sensor as claimed in claim 10, wherein said switch unit and said signal processing unit are connected to different ground lines.

13. An MI sensor, comprising:

an MI element; and

an IC chip for providing an exciting current to the MI element via an MI element electrode;

wherein said IC chip comprises:

a switch unit that, in response to a pulse signal, provides the MI element with the exciting current via the MI element electrode; and

a signal processing unit that receives a detected signal from said MI element and processes

the received detected signal; and

electric power is provided to said switch unit and said signal processing unit through different power supply wirings.

14. The MI sensor as claimed in claim 13, wherein said switch unit and said signal processing unit are connected to different ground lines.

15. An electronic apparatus into which said MI sensor as claimed in claim 8 is built.